







## THIN FILMS

### **Thermal stability and mechanical properties of amorphous coatings in the Ti-B-Si-Al-N system grown by cathodic arc evaporation from TiB<sub>2</sub>, Ti<sub>33</sub>Al<sub>67</sub>, and Ti<sub>85</sub>Si<sub>15</sub> cathodes**

Hanna Fager, Jon M. Andersson, Jens Jensen, Jun Lu and Lars Hultman

J. Vac. Sci. Technol. A **32**, 061508 (2014); <http://dx.doi.org/10.1116/1.4897170>

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### **Synthesis and characterization of large-grain solid-phase crystallized polycrystalline silicon thin films**

Avishek Kumar, Felix Law, Goutam K. Dalapati, Gomathy S. Subramanian, Per I.

Widenborg, Hui R. Tan and Armin G. Aberle

J. Vac. Sci. Technol. A **32**, 061509 (2014); <http://dx.doi.org/10.1116/1.4897298>

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### **Application of cluster-plus-gluon-atom model to barrierless Cu-Ni-Ti and Cu-Ni-Ta films**

Xiaona Li, Jianxin Ding, Miao Wang, Jinn P. Chu and Chuang Dong

J. Vac. Sci. Technol. A **32**, 061510 (2014); <http://dx.doi.org/10.1116/1.4897616>

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### **Characterization of tungsten films and their hydrogen permeability**

Vincenc Nemanič, Janez Kovač, Cristian Lungu, Corneliu Porosnicu and Bojan Zajec

J. Vac. Sci. Technol. A **32**, 061511 (2014); <http://dx.doi.org/10.1116/1.4898061>

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### **Influence of interfacial layer thickness on frequency dependent dielectric properties and electrical conductivity in Al/Bi<sub>4</sub>Ti<sub>3</sub>O<sub>12</sub>/p-Si structures**

Perihan Durmuş and Mert Yıldırım

J. Vac. Sci. Technol. A **32**, 061512 (2014); <http://dx.doi.org/10.1116/1.4900533>

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### **Distribution of ion current density on a rotating spherical cap substrate during ion-assisted deposition**

Viktor Marushka, Oleg Zabeida and Ludvik Martinu

J. Vac. Sci. Technol. A **32**, 061513 (2014); <http://dx.doi.org/10.1116/1.4900541>

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### **Effect of UV curing time on physical and electrical properties and reliability of low dielectric constant materials**

Kai-Chieh Kao, Wei-Yuan Chang, Yu-Min Chang, Jihperng Leu and Yi-Lung Cheng

J. Vac. Sci. Technol. A **32**, 061514 (2014); <http://dx.doi.org/10.1116/1.4900854>

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